Eurocircuits GmbH

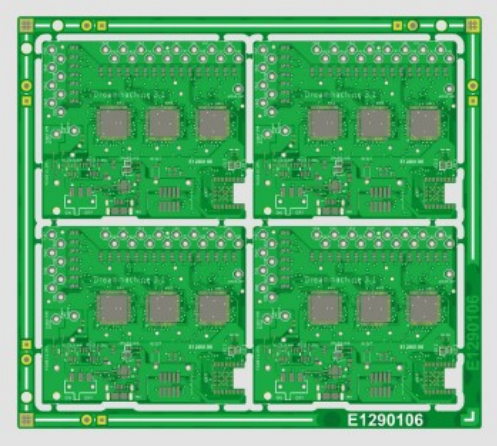
Hauptstrasse 16
57612 - Kettenhausen
Germany
Tel.: +49 2401 91750
Fax: +49 2681 4658
Vat no. / BTW-nummer :
euro@eurocircuits.com

PCB Passport

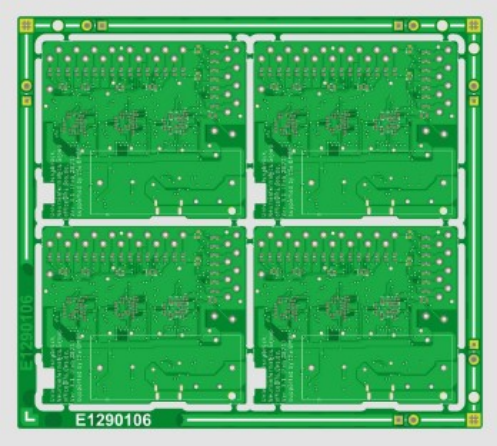
Order Number: E1290106

PCB name : DreamMachine_3_16	Purchase reference :	Quantity packed : 5
Article reference :		Packing date : 02-03-2021
Project reference :		Producer : Eurocircuits Kft.

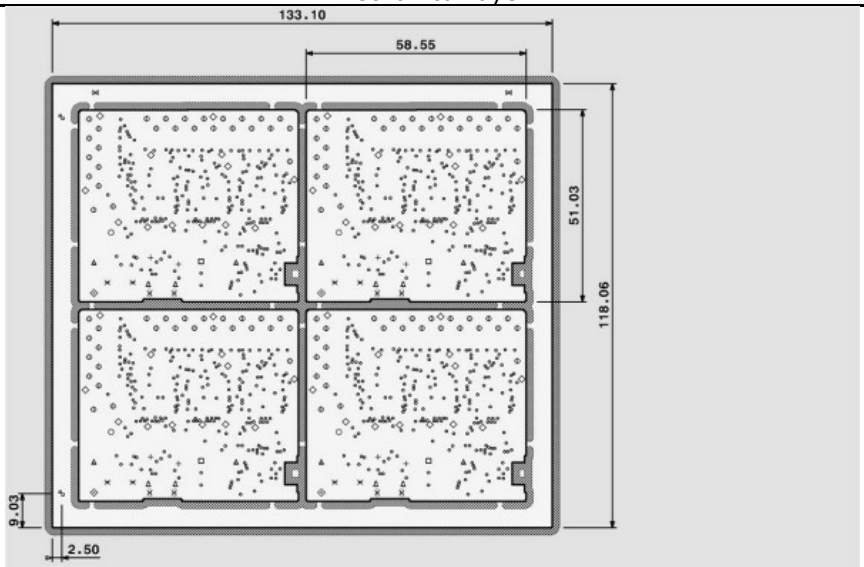
Top view of the PCB



Bottom view of the PCB



Mechanical layer



Layer: E1290106-60

Symbol	Type	Kind	End Dia (mm)	Tool Dia (mm)	Count	+ Tol	- Tol
◦	Via	Drill	0.25	0.35	996	0.10	0.10
△	Plated	Slot	0.55	0.65	8	0.20	0.20
+	Via	Drill	0.65	0.75	8	0.10	0.10
×	Plated	Slot	0.70	0.80	8	0.20	0.20
◇	Via	Drill	0.75	0.85	52	0.10	0.10
□	Via	Drill	0.85	0.95	4	0.10	0.10
×	Plated	Drill	0.90	1.00	8	0.10	0.10
○	Via	Drill	1.00	1.10	4	0.10	0.10
◇	Plated	Drill	1.10	1.20	108	0.10	0.10
△	Plated	Drill	1.20	1.30	8	0.10	0.10

Layer: E1290106-70

Symbol	Type	Kind	End Dia (mm)	Tool Dia (mm)	Count	+ Tol	- Tol
◦	UnplatedECTooling	Drill	3.00	3.00	2	0.05	0.05

⊠	Unplated	Drill	3.00	3.00	2	0.05	0.05
◈	Unplated	Drill	2.00	2.00	4	0.05	0.05

EURO CIRCUITS

PCB Passport

Order Number: E1290106

Production flow of inner layers (02/03)

Production Step	End of the process	Used materials/Specified ordervalues	Tolerances/Result
Start of production	01-03-2021	IS 400 0,71 mm 35/35 um https://www.isola-group.com/products/all-printed-circuit-materials/is400/	Pass
Inner layer imaging	01-03-2021	Type of dry resist foil: Ordyl ALPHA340	Pass
Innerlayer etching	01-03-2021	IL TW: 0,150 mm IL TT-TP-PP: 0,150 mm IL AR: 0,125 mm	Pass
Innerlayer optical test	01-03-2021		Pass

Production flow of outer layers

Multilayer pressing	02-03-2021	Prepreg: PREPREG 7628 IS400 (w460x610) https://www.isola-group.com/products/all-printed-circuit-materials/is400/ Thickness of copper foil: 35 um	Pass
Drilling	02-03-2021	Smallest finished hole size: 0,25 mm	Pass
Pth	02-03-2021	Black hole	Pass
Outer layer imaging	02-03-2021	Type of dry resist foil: Riston PM250	Pass
Outer layer galvano	02-03-2021	Value of copper thickness in the holes: 30-37 um	Pass (min. 18 um)
Outer layer etching	02-03-2021	OL TW: 0,150 mm OL TT-TP-PP: 0,150 mm OL AR: 0,125 mm	Pass
Solderresist coating	02-03-2021	91583543 IMC5009R Green HF DI SC (R): EJ01 91584456 IMC5009H Clear HF DI SC (H): CK10	Pass
Legend	02-03-2021	Taiyo IJR-4000	Pass
Surface finish	02-03-2021	Chemical Ni/Au	Pass
Electrical test	02-03-2021		Pass
Mechanical finishing	02-03-2021	Outline milling	Pass (+/-0,2 mm)
Final inspection	02-03-2021		Pass

Assembly		
MPN	**Ref_des**	**Manufacturer**
TPS73233DBVT	VCC3.3_DIG,VCC3.3_AN	Texas Instruments
TPD4E1B06DRLR	ESD7,ESD6,ESD5,ESD4,ESD3,ESD2, ESD1,	Texas Instruments
TL3780AF330QG	RESET	TE Connectivity
SML-P11MTT86R	LED2,LED1	Rohm
SHF-105-01-L-D-SM-TR	J1	Samtec Inc.
REF3312AIDCKR	D1	Texas Instruments
JS102011SAQN	S1	C&K Components
DSC1001DI5-008.1920T	CLOCK	Microchip Technology
BQ24072TRGTR	CHARGING	Texas Instruments
BC832	BC832	FANSTEL
AD7779ACPZ	ADC3,ADC2,ADC1	Analog Device
CRCW020149K9FKED	R65	Vishay
CRCW020141K2FNED	R57,R56,R55,R49	Vishay Dale
RC0201JR-07300RL	R58,R47,R45	Yageo
ERJ-1GNF3001C	R53	Panasonic Electronic Components
2040002-1	J3	TE Connectivity
CRCW0201200KFNED	R62	Vishay
RC0201JR-072K7L	R68,R41	Yageo
02016D225MAT2A	C33,C23,C22,C19,C3	AVX Corporation
CRCW02012K20JNED	R51	Vishay
RC0201JR-072KL	R69,R43	Yageo
150060RS75000	LED4,LED3	Würth Elektronik
1051	U2	Keystone Electronics
EMK107BBJ106MA-T	C56,C55	Taiyo Yuden
885012105006	C51,C40,C39,C38,C37,C32, C31,C30,C29,C28,C27,C26, C25,C24,C21,C18,C17,C16, C15,C14,C13,C12,C11,C9, C8,C7,C6,C4,C2,C1,	Wurth Electronics
LMK063C6104KP-F	C87,C86,C85,C84,C83,C82, C81,C79,C78,C77,C75,C74, C73,C72,C71,C70,C69,C68, C67,C66,C65,C64,C20,	Taiyo Yuden
GRM033R61E103MA12J	C57,C10,C5	Murata Electronics
MCWR06X000 PTL	R54,R52,R50,R48,R46,R44, R42,R40,R39,R38,R37,R36, R35,R34,R33,R32,R31,R30, R29,R28,R27,R26,R25,R24, R23,R22,R21,R20,R19,R18, R17,R16,R15,R14,R13,R12, R11,R10,R9,R8,R7,R6, R5,R4,R3,R2,R1,	Mutlcomp

Top SMD view

No image available

Bottom SMD view

No image available

Production Flow-Assembly			
Production Step	**End of the process**	**Used materials/Specified ordervalues**	**Tolerances/Result**
Start of Production	01/03/2021	BoM:E1290106-A	Pass
Marking check			Pass
Feeder preparation			Pass
Pasting - BOT			Pass
Paste printing + Automatic inspection		Leadfree solderalloy.	Pass
First board - BOT (AUTO)			Pass
PixPect PASTE			Pass
Reflow - BOT first board			Pass
SMD inspection			Pass
X-ray inspection			Pass
All boards - BOT (AUTO)			Pass
Reflow - BOT all boards			Pass
SMD inspection			Pass
X-ray inspection			Pass
Pasting - TOP			Pass
Paste printing + Automatic inspection		Leadfree solderalloy.	Pass
First board - TOP (AUTO)			Pass
PixPect PASTE			Pass
Reflow - TOP first board			Pass
SMD inspection			Pass
X-ray inspection			Pass
Top SMD assembly		Used reflow profile:	Pass
Reflow - TOP all boards			Pass
PixPect remained boards			Pass
SMD inspection			Pass
X-ray inspection			Pass
Through Hole component mounting		Used reflow profile:	Pass
THT PixPect			Pass
Final inspection			Pass
THT all boards - TOP (MANUAL)			Pass
THT PixPect			Pass
Final inspection			Pass
Washing			Pass
Breakout / polish			Pass
Packing & shipping			Pass